

Application No.: 10/772,510

Filed: February 5, 2004

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Reply to Office Action of February 5, 2007

a.) Amendments to Specification

*Replace the paragraph [0006] beginning at page 1 in the specification as published with the following rewritten paragraph:*

[0006] moving a camera, having an image field field, over a wafer and thereby acquiring with its image field a plurality of images;

*Replace the paragraph [0009] beginning at page 1 in the specification as published with the following rewritten paragraph:*

[0009] It is an other object of the invention to make available an apparatus for the analysis of surface images of wafers, wherein the apparatus performs comparisons of optical images in an efficient way.

*Replace the paragraph [0049] beginning at page 3 in the specification as published with the following rewritten paragraph:*

[0049] When the two indices are combined, the first segment receives the index 16 - 1a. The first camera image encompasses image field segments 16 - 1a, 2b, 4c, 5d. The second camera image encompasses image field segments 16 - 3a, 1b, 6c, 4d, etc. The contents of the first and fourth images 16 can be compared with one another, since they match in terms of both SAW index and image index.